OPTI9000

2D/3D Automated Inspection System

OPTI9000 offers high speed, in-tray, 2D and 3D inspection. Providing both high throughput and high resolution, OptiViz's proprietary 3D laser scanning technology and 2D inspection modules are the ideal combination for speed and accuracy while balancing cost of ownership.

The unique scanner and multi-camera combination provides unprecedented flexibility in inspecting various devices types without the need for change-out kits. The multi-illumination module allows for the most subtle defects to be detected.

The OPTI9000 series system provides fully automated tray handling, stacking and sorting. The system is extendable to support both current and future inspection requirements at every process stage; all without compromising accuracy, repeatability and throughput.

Inspects ball/lead package types

Reliable shuttle tray transfer

User-friendly interface

Single-point operator access

Precision handling system
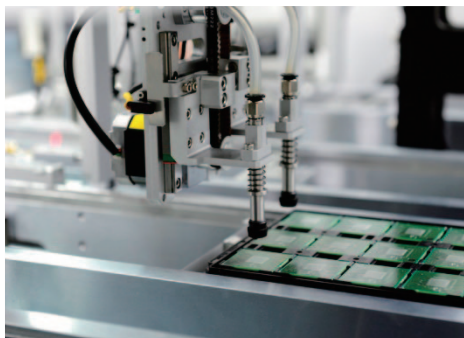
Automatic device conversion

Windows operating system

Proven/simplistic handling system
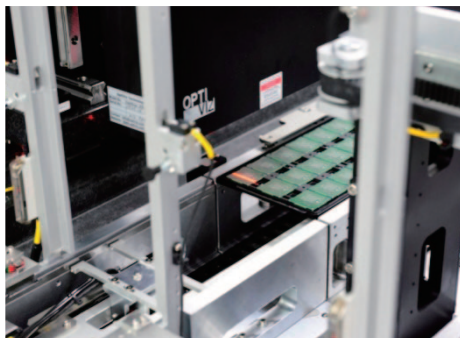
OptiViz Technology Inc.

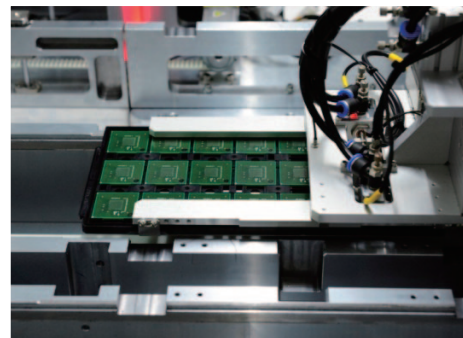# High Performance with High Flexibility

3D Package Inspection System

High Speed Auto Pitch Sorting Module

The dual-head pick & place provides speed , precision and reliability ensuring the device integrity is maintained.

High Precision Laser Scanner Module

The solid state scanner provides the best combination of precision, speed and reliability.

Tray Handling

The tray handling system pipelines all trays simultaneously; optimizing throughput and ensuring accurate positioning.

3D System Configuration

3D Laser + High Precision X/Y/Z Motion Gantry

Device Types
-QFP,TSOP,BGA,CSP and others

Inspection Items

Coplanarity , Warpage , Height , Thickness , Pitch , Package X/Y ……..

Inspection Capability

Standard Laser 3D

5 microns accuracy & repeatability on Z measurement

High Resolution Laser 3D

1 micron accuracy & repeatability on Z measurement

2D Module Configuration

High Resolution CCD + Multiple Channel Lighting

Inspection Items

Marking Quality / Orientation / Scratch / Particle / Void / Chip-out / ….
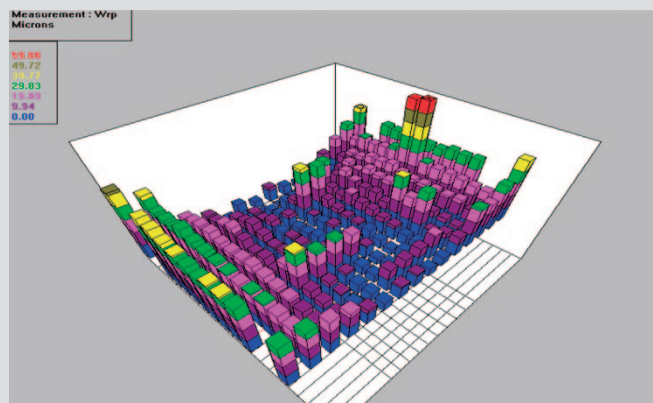General 2D Dimension Measurement such as point-to-point, point-to-line, Angle , Diameter, …

Option

Auto Zoom / Auto Focus Capability

SPECIFICATION SUMMARY

CONFIGURATION

Base Configuration

-3D scanner module and
 precision X/Y/Z gantry
-Replenish tray x1
-Binning trays x2
-PnP:2 heads with auto pitch

Measurement : Wrp
Microns

PERFORMANCE

Lead Devices
-Coplanarity
-Pitch X/Y
-Lead Width
-Package Stand-off
-Package Warpage

Ball Devices
-Coplanarity
-Pitch X/Y
-Ball Width
-Package Stand-off
-Package Warpage

Bump Devices
-Coplanarity
-Pitch X/Y
-Bump Width
-Bump Height
-Warpage

OptiViz

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